

RD3R02BBH

Nch 150V 20A Power MOSFET

V _{DSS}	150V
R _{DS(on)} (Max.)	81mΩ
I _D	±20A
P _D	50W

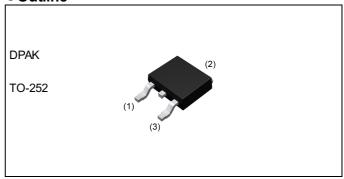
Features

- 1) Low on resistance
- 2) High Power Package(TO-252)
- 3) Pb-free plating; RoHS compliant
- 4) Halogen Free

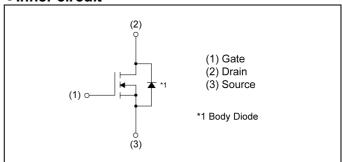


Switching

Outline



●Inner circuit



Packaging specifications

● F ackaţ	Jing specifications	
	Packing	Embossed Tape
	Reel size (mm)	330
Type	Tape width (mm)	16
	Quantity (pcs)	2500
	Taping code	TL1
	Marking	RD3R02BBH

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		V _{DSS}	150	V
Continuous drain current	Continuous drain current V _{GS} = 10V		±20	Α
Pulsed drain current		I _{DP} *2	±80	Α
Gate - Source voltage		V _{GSS}	±20	V
Avalanche current, single pulse		I _{AS} *3	13	А
Avalanche energy, single pulse		E _{AS} *3	6.6	mJ
Power dissipation		P _D *1	50	W
Junction temperature		T _j	150	°C
Operating junction and storage ter	T _{stg}	-55 to +150	°C	

●Thermal resistance

Parameter	Symbol	Values			Lloit
		Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *1	-	1	2.50	°C/W

● Electrical characteristics (T_a = 25°C)

Davamatav	Cymah al	Conditions	Values			I loit
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		150	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D = 1mA referenced to 25°C	-	98	-	mV/°C
Zero gate voltage drain current	I _{DSS} V _{DS} = 150V, V _{GS} = 0V		-	-	5	μΑ
Gate - Source leakage current	I _{GSS}	I_{GSS} $V_{GS} = \pm 20V, V_{DS} = 0V$		ı	±500	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{GS(th)}$ $V_{DS} = V_{GS}$, $I_D = 1mA$		-	4.0	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = 1mA referenced to 25°C	-	-5.7	-	mV/°C
Static drain - source	D *4	V _{GS} = 10V, I _D = 10A	-	62	81	mO.
on - state resistance	R _{DS(on)} *4	V _{GS} = 6V, I _D = 10A	-	67	100	mΩ
Gate resistance	R _G -		-	1.5	-	Ω
Forward Transfer Admittance	Y _{fs} *4	V _{DS} = 5V, I _D = 10A	7.1	-	-	S

^{*1} T_c=25°C, Limited only by maximum temperature allowed.

^{*2} Pw≤ 10µs , Duty cycle≤ 1%

^{*3} L \simeq 0.1mH, V_{DD} = 75V, R_G = 25 Ω , Starting T_i = 25 $^{\circ}$ C Fig.3-1,3-2

^{*4} Pulsed

● Electrical characteristics (T_a = 25°C)

Parameter	Cymahal	Conditions		Unit			
Parameter	Symbol Conditions —		Min.	Тур.	Max.	UIIIL	
Input capacitance	C _{iss}	V _{GS} = 0V	-	730	-		
Output capacitance	C _{oss}	V _{DS} = 75V	-	65	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	12	-		
Turn - on delay time	t _{d(on)} *4	V _{DD} ≈ 75V,V _{GS} = 10V	1	14	1		
Rise time	t _r *4	I _D = 10A	ı	10	1	no	
Turn - off delay time	t _{d(off)} *4	$R_L \simeq 7.5\Omega$	-	28	-	ns	
Fall time	t _f *4	$R_G = 10\Omega$	-	13	-		

● Gate charge characteristics (T_a = 25°C)

Doromotor	Cymahal	Conditions		Values			1.124
Parameter	Symbol			Min.	Тур.	Max.	Unit
Total gate charge	O *4		V _{GS} = 10V	-	12.4	-	
Total gate charge	Q _g *4	V _{DD} ≃ 75V		-	8.1	-	" C
Gate - Source charge	Q _{gs} *4	I _D = 20A	V _{GS} = 6V	-	2.7	-	nC
Gate - Drain charge	Q _{gd} *4			-	3.3	-	

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Darameter	Symbol	Conditions	Values			Unit
Parameter Symbol Conditions		Min.	Тур.	Max.	Offic	
Continuous forward current	I _S	T _a = 25°C	1	1	20	Α
Pulse forward current	I _{SP} *2	1 _a - 25 C	-	-	80	Α
Forward voltage	V _{SD} *4	$V_{GS} = 0V, I_{S} = 20A$	-	-	1.2	V
Reverse recovery time	t _{rr} *4	I _S = 20A, V _{GS} =0V	-	110	-	ns
Reverse recovery charge	Q _{rr} *4	di/dt = 100A/μs	-	345	-	nC

Fig.1 Power Dissipation Derating Curve

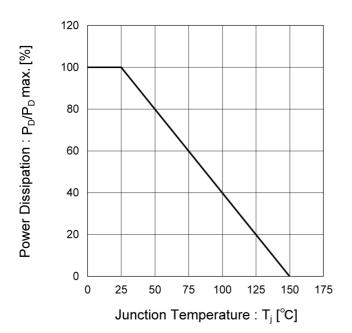
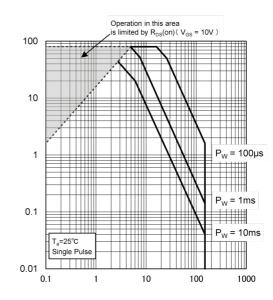


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Drain - Source Voltage: V_{DS}[V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

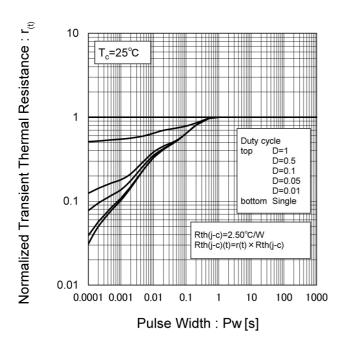


Fig.4 Single Pulse Maximum Power Dissipation

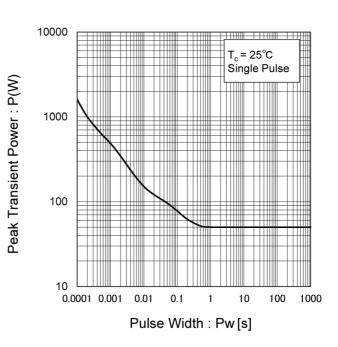
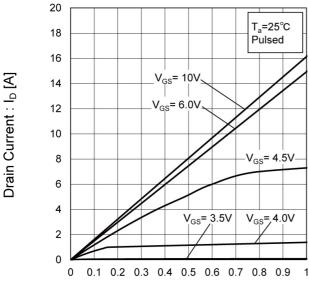
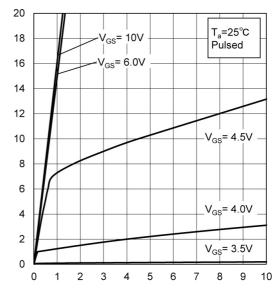


Fig.5 Typical Output Characteristics(I)



Drain - Source Voltage : $V_{DS}[V]$

Fig.6 Typical Output Characteristics(II)



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.7 Breakdown Voltage vs.
Junction Temperature

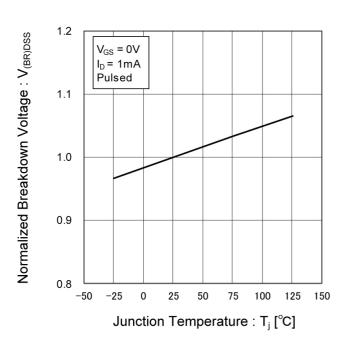
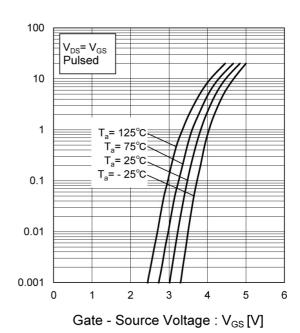


Fig.8 Typical Transfer Characteristics



Drain Current : I_D [A]

Fig.9 Gate Threshold Voltage vs.
Junction Temperature

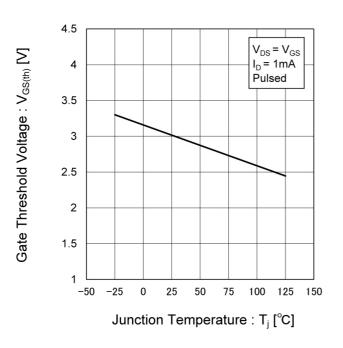


Fig.10 Forward Transfer Admittance vs.
Drain Current

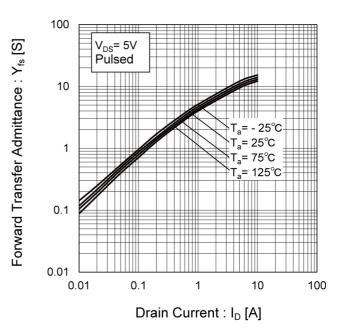


Fig.11 Drain Current Derating Curve

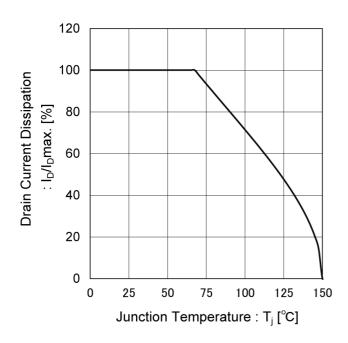


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

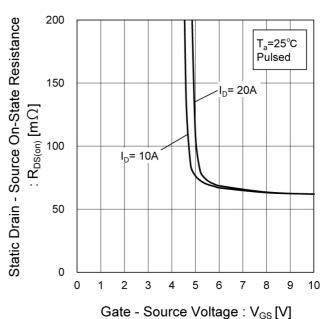


Fig.13 Static Drain - Source On - State
Resistance vs. Junction Temperature

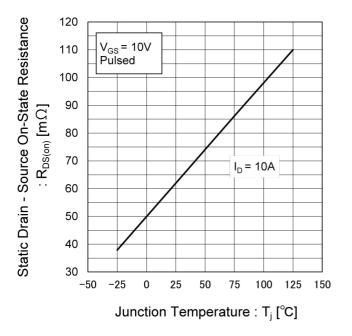


Fig.14 Static Drain - Source On - State
Resistance vs. Drain Current (I)

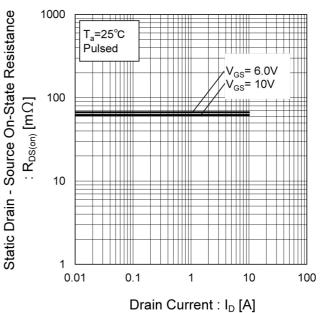


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

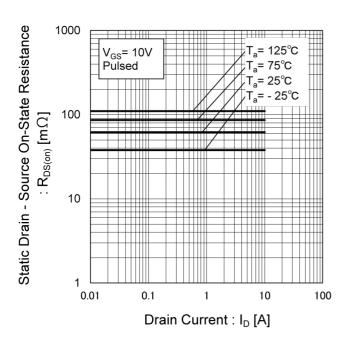


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

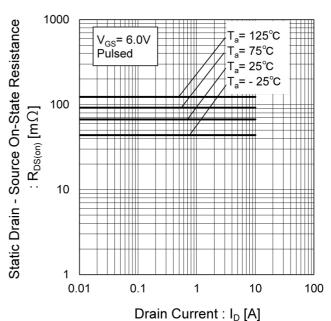
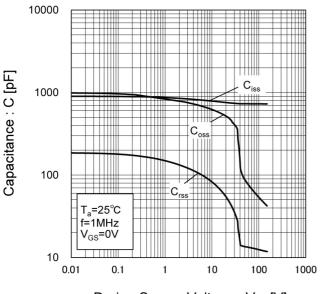


Fig.17 Typical Capacitances vs.

Drain - Source Voltage



Drain - Source Voltage : $V_{DS}[V]$

Fig.18 Switching Characteristics

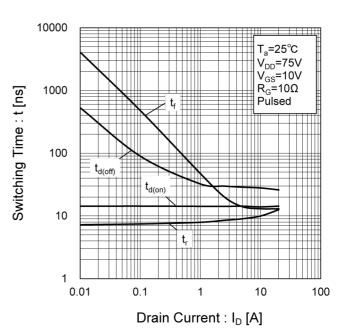


Fig.19 Typical Gate Charge

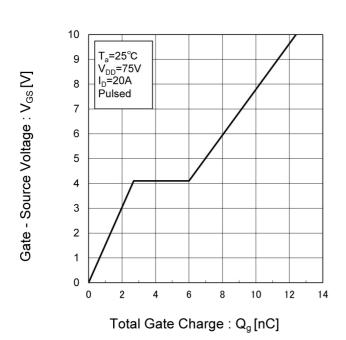
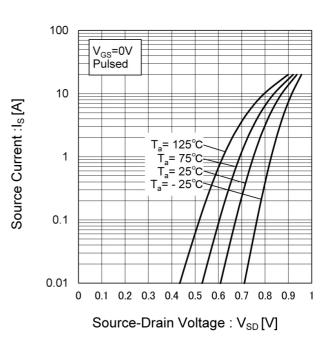


Fig.20 Source Current vs.

Source Drain Voltage



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

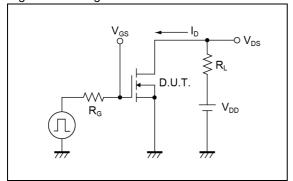


Fig.1-2 Switching Waveforms

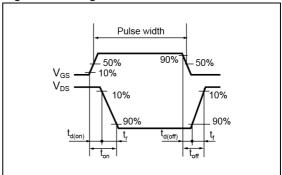


Fig.2-1 Gate Charge Measurement Circuit

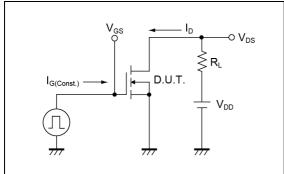


Fig.2-2 Gate Charge Waveform

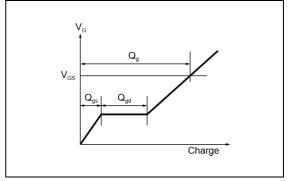


Fig.3-1 Avalanche Measurement Circuit

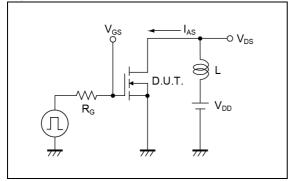
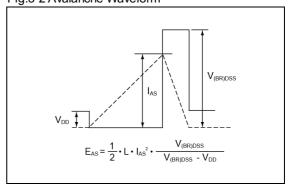
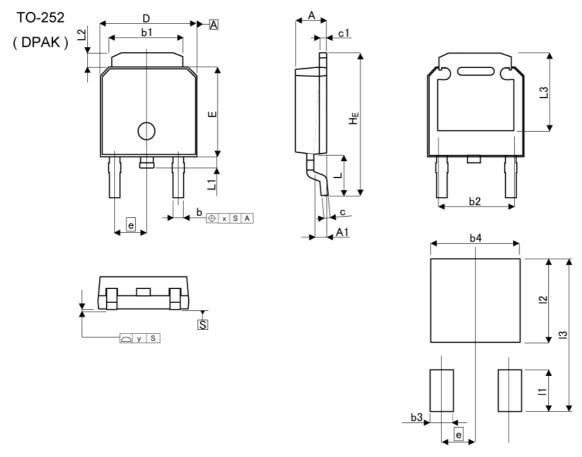


Fig.3-2 Avalanche Waveform



Dimensions



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.20	2.40	0.087	0.094
A1	0.70	1.10	0.028	0.043
b	0.60	0.90	0.024	0.035
b1	5.20	5.50	0.205	0.217
b2	4.	80	0.1	89
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.0	91
E	6.00	6.40	0.236	0.252
HE	9.40	10.40	0.370	0.409
L	2.	90	0.1	14
L1	0.60	1.00	0.024	0.039
L2	0.70	1.30	0.028	0.051
L3	5.	5.30 0.209		209
X	-	0.25	-	0.010
у	-	0.10	, - .	0.004
DIM	MILIME	TERS	INCHES	
DIM	MIN	MAX	MIN	MAX
b3	-	1.15	[[-7	0.045
b4	-	5.55	(.	0.219
I1	-	2.77	-	0.109
12	-	5.50	(-)	0.217
13	=	10.40	-	0.409

Dimension in mm/inches



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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
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- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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